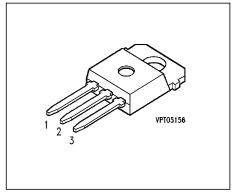


**BUZ 345** 

## **SIPMOS** ® **Power Transistor**

- N channel
- Enhancement mode
- Avalanche-rated



Pin 1	Pin 2	Pin 3
G	D	S

Туре	V <sub>DS</sub>	I <sub>D</sub>	R <sub>DS(on)</sub>	Package	Ordering Code
BUZ 345	100 V	41 A	$0.045~\Omega$	TO-218 AA	C67078-S3121-A2

#### **Maximum Ratings**

Parameter	Symbol	Values	Unit
Continuous drain current	I <sub>D</sub>		Α
$T_{\rm C}$ = 28 °C		41	
Pulsed drain current	I <sub>Dpuls</sub>		
$T_{\rm C}$ = 25 °C		164	
Avalanche current, limited by $T_{jmax}$	I <sub>AR</sub>	41	
Avalanche energy,periodic limited by $T_{ m jmax}$	E <sub>AR</sub>	18	mJ
Avalanche energy, single pulse	E <sub>AS</sub>		
$I_{D}$ = 41 A, $V_{DD}$ = 25 V, $R_{GS}$ = 25 $\Omega$			
$L = 249.9 \mu\text{H},  T_{j} = 25 ^{\circ}\text{C}$		280	
Gate source voltage	$V_{GS}$	± 20	V
Power dissipation	P <sub>tot</sub>		W
$T_{\rm C}$ = 25 °C		150	
Operating temperature	T <sub>j</sub>	-55 <b>+</b> 150	°C
Storage temperature	T <sub>stg</sub>	-55 <b>+</b> 150	
Thermal resistance, chip case	R <sub>thJC</sub>	≤ 0.83	K/W
Thermal resistance, chip to ambient	R <sub>thJA</sub>	75	
DIN humidity category, DIN 40 040		E	
IEC climatic category, DIN IEC 68-1		55 / 150 / 56	



# **Electrical Characteristics,** at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain- source breakdown voltage	V <sub>(BR)DSS</sub>				V
$V_{\rm GS}$ = 0 V, $I_{\rm D}$ = 0.25 mA, $T_{\rm j}$ = 25 °C		100	-	-	
Gate threshold voltage	V <sub>GS(th)</sub>				
$V_{\text{GS}} = V_{\text{DS}}$ , $I_{\text{D}} = 1 \text{ mA}$		2.1	3	4	
Zero gate voltage drain current	l <sub>DSS</sub>				μΑ
$V_{\rm DS} = 100 \text{ V}, \ V_{\rm GS} = 0 \text{ V}, \ T_{\rm j} = 25 ^{\circ}\text{C}$		-	0.1	1	
$V_{\rm DS} = 100 \text{ V}, \ V_{\rm GS} = 0 \text{ V}, \ T_{\rm j} = 125 ^{\circ}\text{C}$		-	10	100	
Gate-source leakage current	l <sub>GSS</sub>				nA
$V_{GS} = 20 \text{ V}, \ V_{DS} = 0 \text{ V}$		-	10	100	
Drain-Source on-resistance	R <sub>DS(on)</sub>				Ω
$V_{GS} = 10 \text{ V}, I_D = 26 \text{ A}$		-	0.04	0.045	



# **Electrical Characteristics,** at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Transconductance	$g_{fs}$				S
$V_{DS} \ge 2 * I_D * R_{DS(on)max}, I_D = 26 A$		10	20	-	
Input capacitance	$C_{iss}$				pF
$V_{GS} = 0 \text{ V}, \ V_{DS} = 25 \text{ V}, \ f = 1 \text{ MHz}$		-	1800	2700	
Output capacitance	$C_{oss}$				
$V_{GS} = 0 \text{ V}, \ V_{DS} = 25 \text{ V}, \ f = 1 \text{ MHz}$		-	560	840	
Reverse transfer capacitance	$C_{rss}$				
$V_{GS} = 0 \text{ V}, \ V_{DS} = 25 \text{ V}, \ f = 1 \text{ MHz}$		-	270	400	
Turn-on delay time	t <sub>d(on)</sub>				ns
$V_{\rm DD}$ = 30 V, $V_{\rm GS}$ = 10 V, $I_{\rm D}$ = 3 A					
$R_{\rm GS}$ = 50 $\Omega$		-	30	45	
Rise time	t <sub>r</sub>				
$V_{\rm DD}$ = 30 V, $V_{\rm GS}$ = 10 V, $I_{\rm D}$ = 3 A					
$R_{\rm GS} = 50~\Omega$		-	110	165	
Turn-off delay time	t <sub>d(off)</sub>				
$V_{\rm DD}$ = 30 V, $V_{\rm GS}$ = 10 V, $I_{\rm D}$ = 3 A					
$R_{\rm GS}$ = 50 $\Omega$		-	300	390	
Fall time	t <sub>f</sub>				
$V_{\rm DD}$ = 30 V, $V_{\rm GS}$ = 10 V, $I_{\rm D}$ = 3 A					
$R_{\rm GS}$ = 50 $\Omega$		-	150	195	



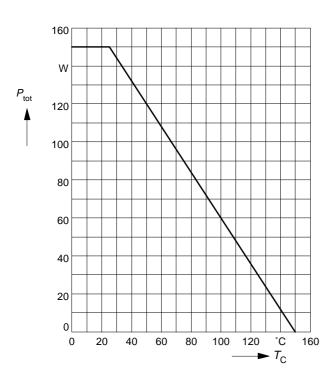
# **Electrical Characteristics**, at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Reverse Diode					
Inverse diode continuous forward current	IS				А
$T_{\rm C}$ = 25 °C		-	-	41	
Inverse diode direct current,pulsed	/ <sub>SM</sub>				
$T_{\rm C}$ = 25 °C		-	-	164	
Inverse diode forward voltage	$V_{\mathrm{SD}}$				V
$V_{GS} = 0 \text{ V}, I_{F} = 82 \text{ A}$		-	1.6	1.8	
Reverse recovery time	t <sub>rr</sub>				ns
$V_{R} = 30 \text{ V}, I_{F} = I_{S,} di_{F}/dt = 100 \text{ A/}\mu\text{s}$		-	120	-	
Reverse recovery charge	Q <sub>rr</sub>				μC
$V_{R} = 30 \text{ V}, I_{F} = I_{S,} di_{F}/dt = 100 \text{ A/}\mu\text{s}$		-	0.6	-	



#### **Power dissipation**

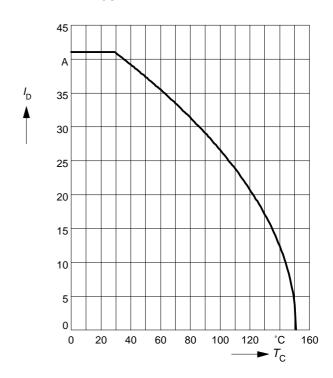
$$P_{\mathsf{tot}} = f(T_{\mathsf{C}})$$



## Drain current

 $I_{\mathsf{D}} = f(T_{\mathsf{C}})$ 

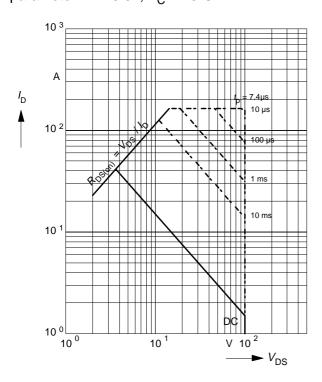
parameter: V<sub>GS</sub> ≥ 10 V



## Safe operating area

 $I_{\mathsf{D}} = f(V_{\mathsf{DS}})$ 

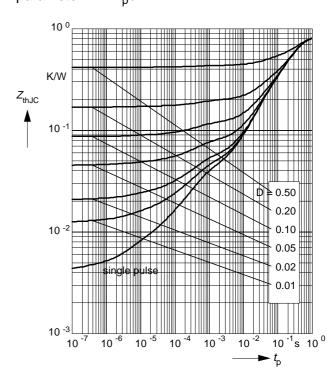
parameter: D = 0.01,  $T_C = 25$ °C



## Transient thermal impedance

 $Z_{\mathsf{th\ JC}} = f(t_{\mathsf{p}})$ 

parameter:  $D = t_p / T$ 

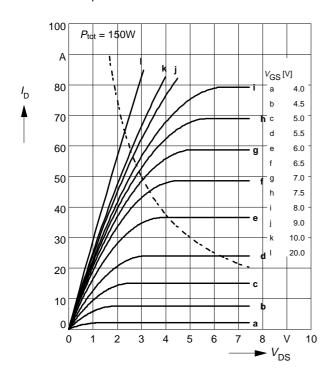




#### Typ. output characteristics

 $I_{\mathsf{D}} = f(V_{\mathsf{DS}})$ 

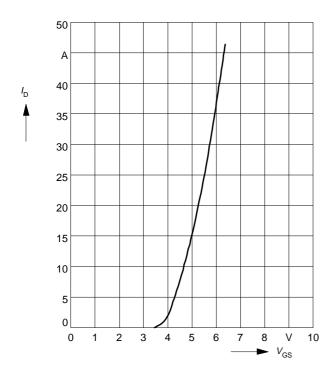
parameter:  $t_p = 80 \mu s$ 



#### Typ. transfer characteristics $I_D = f(V_{GS})$

parameter:  $t_p = 80 \mu s$ 

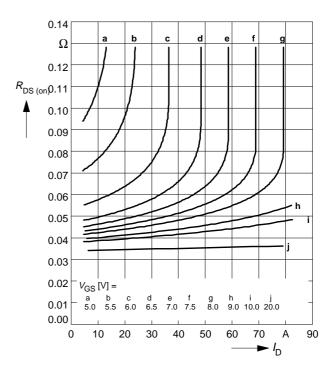
 $V_{DS} \ge 2 \times I_D \times R_{DS(on)max}$ 



#### Typ. drain-source on-resistance

 $R_{\mathrm{DS (on)}} = f(I_{\mathrm{D}})$ 

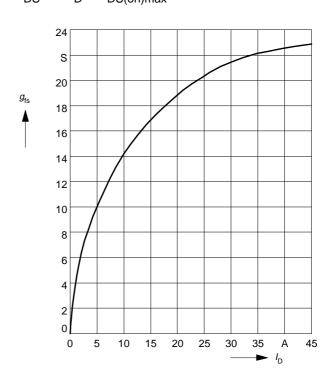
parameter: V<sub>GS</sub>



#### Typ. forward transconductance $g_{fs} = f(I_D)$

parameter:  $t_p = 80 \mu s$ ,

 $V_{\text{DS}} \ge 2 \times I_{\text{D}} \times R_{\text{DS(on)max}}$ 

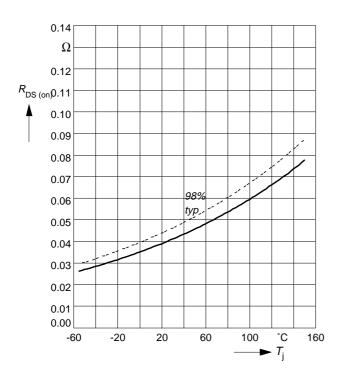




#### **Drain-source on-resistance**

 $R_{DS (on)} = f(T_j)$ 

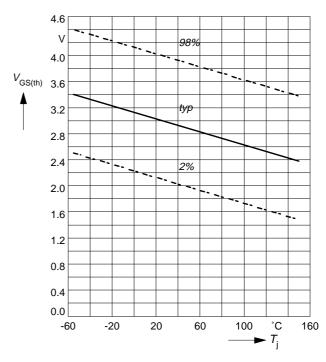
parameter:  $I_D = 26 \text{ A}$ ,  $V_{GS} = 10 \text{ V}$ 



#### Gate threshold voltage

 $V_{GS (th)} = f(T_j)$ 

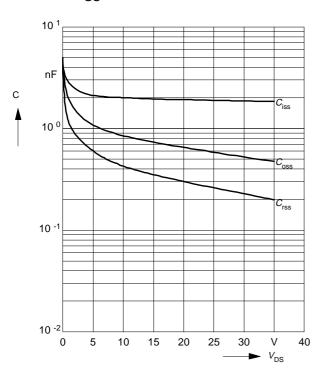
parameter:  $V_{GS} = V_{DS}$ ,  $I_D = 1 \text{ mA}$ 



#### Typ. capacitances

 $C = f(V_{DS})$ 

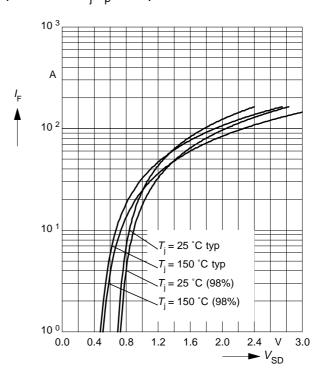
parameter:  $V_{GS} = 0V$ , f = 1MHz



## Forward characteristics of reverse diode

 $I_{\mathsf{F}} = f(V_{\mathsf{SD}})$ 

parameter:  $T_i$ ,  $t_p = 80 \mu s$ 

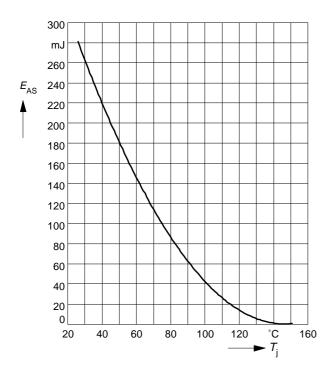




## Avalanche energy $E_{AS} = f(T_j)$

parameter:  $I_D = 41 \text{ A}$ ,  $V_{DD} = 25 \text{ V}$ 

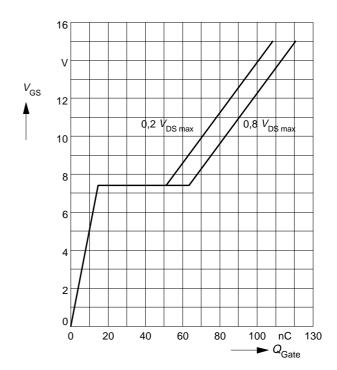
 $R_{\mathrm{GS}}$  = 25  $\Omega$ , L = 249.9  $\mu\mathrm{H}$ 



#### Typ. gate charge

 $V_{\mathsf{GS}} = f(Q_{\mathsf{Gate}})$ 

parameter:  $I_{D \text{ puls}} = 62 \text{ A}$ 



#### Drain-source breakdown voltage

 $V_{(BR)DSS} = f(T_j)$ 

